



# SOT1652-3

FBGA780, plastic, fine-pitch ball grid array; 780 bumps; 0.8 mm pitch; 23 mm x 23 mm x 1.92 mm body

26 February 2019

Package information

## 1 Package summary

|                                       |                                   |
|---------------------------------------|-----------------------------------|
| <b>Terminal position code</b>         | B (bottom)                        |
| <b>Package type descriptive code</b>  | FBGA780                           |
| <b>Package style descriptive code</b> | FBGA (fine-pitch ball grid array) |
| <b>Package body material type</b>     | P (plastic)                       |
| <b>Mounting method type</b>           | S (surface mount)                 |
| <b>Issue date</b>                     | 27-01-2016                        |
| <b>Manufacturer package code</b>      | 98ASA00659D                       |

Table 1. Package summary

| Parameter                      | Min | Nom  | Max  | Unit |
|--------------------------------|-----|------|------|------|
| package length                 | -   | 23   | -    | mm   |
| package width                  | -   | 23   | -    | mm   |
| seated height                  | -   | 1.92 | 2.07 | mm   |
| nominal pitch                  | -   | 0.8  | -    | mm   |
| actual quantity of termination | -   | 780  | -    |      |





NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

|  |                          |                            |  |
|--|--------------------------|----------------------------|--|
| © NXP SEMICONDUCTORS N.V.<br>ALL RIGHTS RESERVED                       | MECHANICAL OUTLINE       | PRINT VERSION NOT TO SCALE |  |
| TITLE: FCPBGA, NO LID,<br>23 X 23 X 1.92 PKG,<br>0.8 MM PITCH, 780 I/O | DOCUMENT NO: 98ASA00659D | REV: A                     |  |
|  | STANDARD: NON-JEDEC      |                            |  |
|  | SOT1652-3                | 27 JAN 2016                |  |

Figure 2. Package outline note FBGA780 (SOT1652-3)

### 3 Legal information

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